

WE CLAIM AS OUR INVENTION:

1. A two-pole surface mount technology (SMT) miniature housing in leadframe technique for a semiconductor component, comprising:

a housing;

a semiconductor chip encapsulated in the housing;

a first leadframe part having the semiconductor chip mounted thereon at a chip mounting surface thereof and a second leadframe part contacted to the chip, both leadframe parts being conducted out of the housing;

the leadframe parts each forming solder terminals alongside the housing;

solder terminals being formed as punched parts of portions of the leadframe and which run alongside and laterally project outwardly from sidewalls of the housing at opposite sides of the housing, said solder terminals extending vertically downwardly to at least a position substantially level with a floor of the housing that forms a mounting surface for the component; and

said chip mounting surface and said component mounting surface formed by said housing floor being at right angles with respect to one another.

2. A housing according to claim 1 wherein the solder terminals have a thickness of approximately .2 mm - .5 mm.

3. A housing according to claim 1 wherein the semiconductor component comprises an optoelectronic component.

4. A housing according to claim 1 wherein the semiconductor chip is a laterally receiving optoelectronic component.

5. A housing according to claim 1 wherein the semiconductor chip is a laterally transmitting optoelectronic component.

6. A surface mount technology component, comprising:

- a housing having a flat mounting surface for mounting the component on a printed circuit board;
- a semiconductor chip encapsulated in the housing;
- first and second leadframe parts contacted to the semiconductor chip, at least one of said leadframe parts being directly mounted to the semiconductor chip at a flat mounting surface thereof;
- said first and second leadframe parts being conducted out of said housing and forming solder terminals extending along opposite sides of the housing and outwardly from the housing, said solder terminals terminating at least level with said housing mounting surface;
- said first and second leadframe parts being planar throughout their extent and comprising punched parts;
- the mounting surface of the chip being at right angles to said housing mounting surface; and
- planar surfaces of said solder terminals being at right angles to said housing mounting surface.

7. A method for manufacturing a two-pole surface mount technology (SMT) miniature housing in leadframe technique for a semiconductor component, comprising the steps of:

- punching out first and second leadframe parts having a portion extending into the housing and a leg portion serving as respective solder terminals running at right angles to the portion extending into the housing;

- mounting a semiconductor chip on the first leadframe part at a flat mounting surface of the chip and contacting the semiconductor chip to the other leadframe part;
- and

encapsulating the semiconductor chip in a housing such that said right-angled leg portions of the leadframe parts forming solder terminals are positioned at two opposite sides of the housing and extend at least to a floor of the housing serving as a mounting surface for the housing, a right angle being provided between said chip flat mounting surface and a bottom of the housing serving as a mounting surface for the component.